

# Trends for Integrated Isolated DC/DC Conversion in Automotive Applications

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**Texas Instruments -- Kilby Labs**

TI Information-- Selective Disclosure

# Introduction

- Jeffrey Morroni
  - Director of Kilby Labs Power Management
  - PhD in Power Electronics from University of Colorado, Boulder
  - Joined TI with the National Semiconductor acquisition
  - Based in Dallas



# Cars of the Future...Now

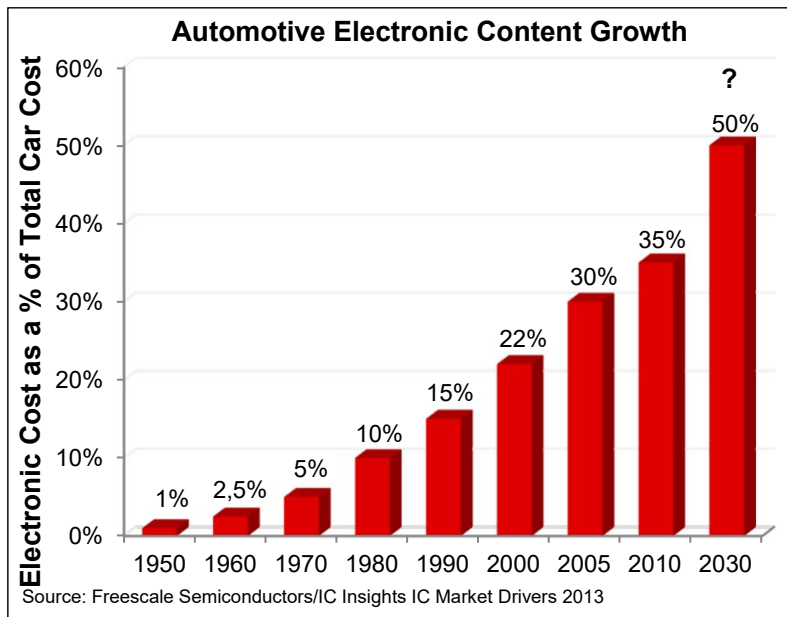
*2000 Model Year Toyota Camry*



*2020 Model Year Toyota Camry Hybrid*



# Automotive Drive for More Electronics



- Electronic systems account for 1/3 of new vehicles cost
- 41% analog IC and 39% microcontroller

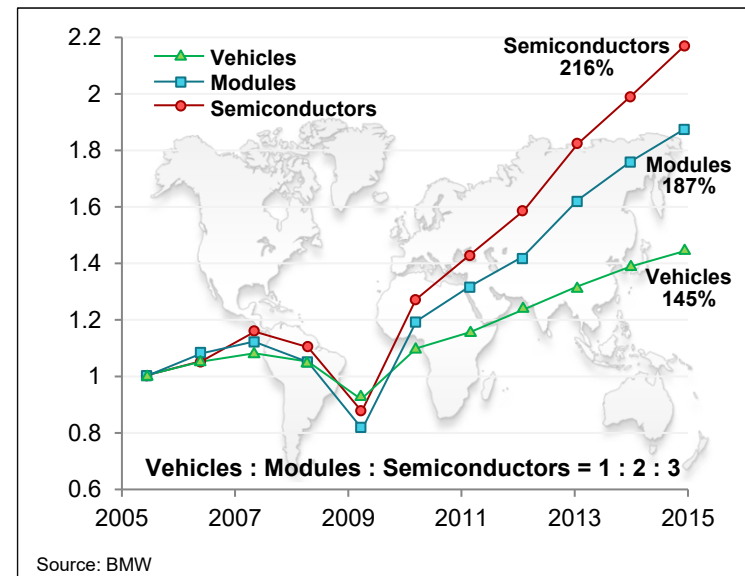
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## More than 8000 Semiconductor devices in a car

### Power Management:

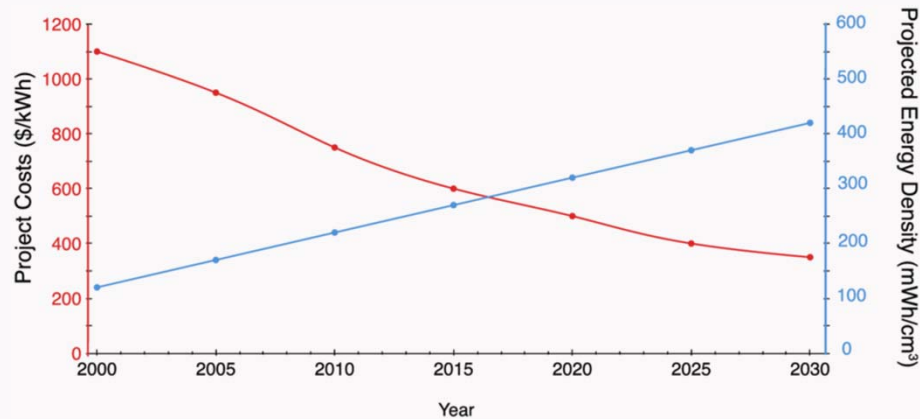
Battery Management  
Adaptive lighting  
POL Power...

Wireless Power  
Universal charger



# Moore vs. Goodenough

Battery Energy and Cost vs. Time



\*Source: Enabling technologies for autonomous MAV operations

- Battery energy density have doubled every ~120 months
- Transistors have historically doubled every 24 months
- If batteries had followed Moore's law
  - 300 mile range
  - \$1 battery
  - That would fit in the palm of your hand!

- More electronics, similar batteries → Power management innovations required to sustain

# EV/HEV Needs High Voltage Power Products

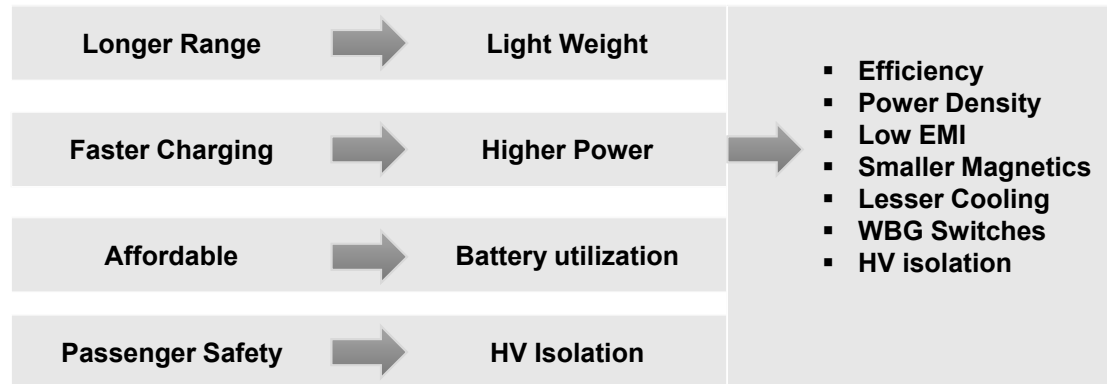
## HEV/EV Needs



## Vehicle Implications



## Power System Implications

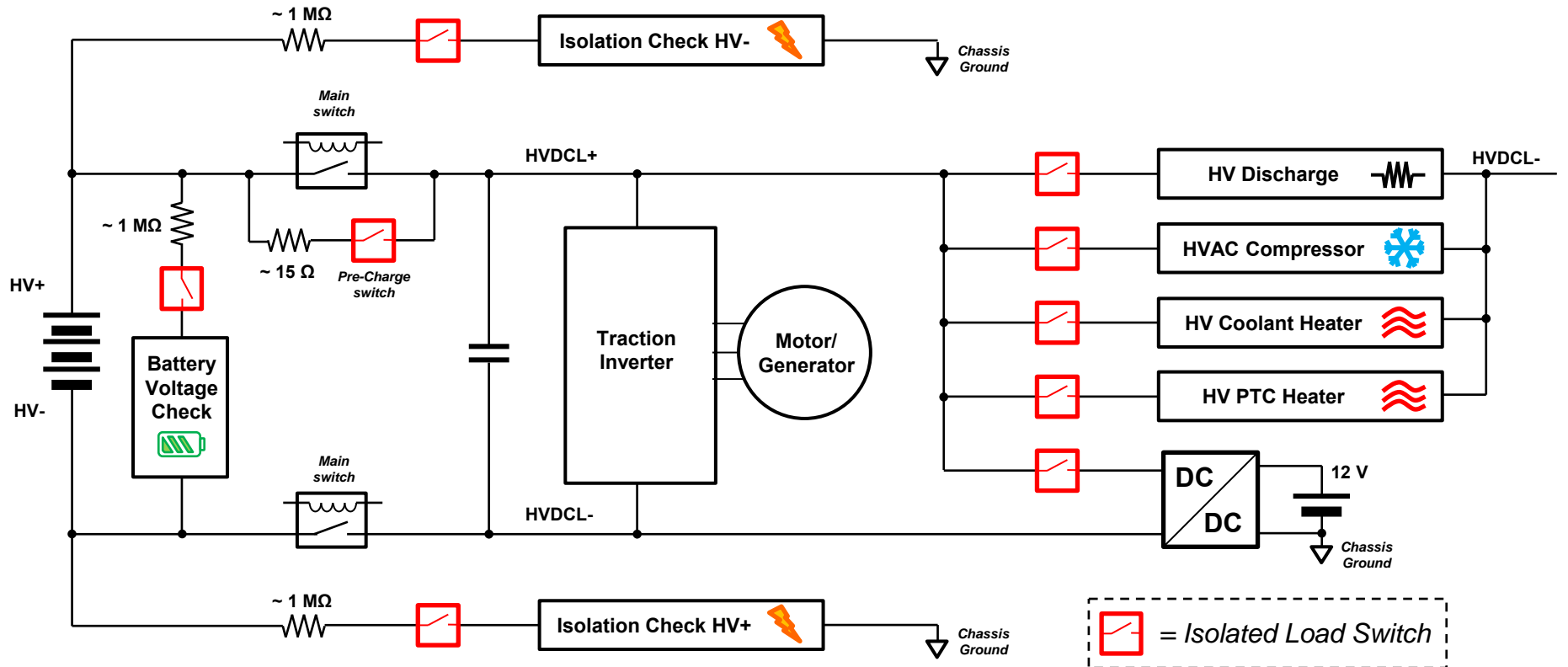


Driving a path towards more power supplies on chip

# Application for Solid State Relays

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# Automotive EV/HEV Application Overview

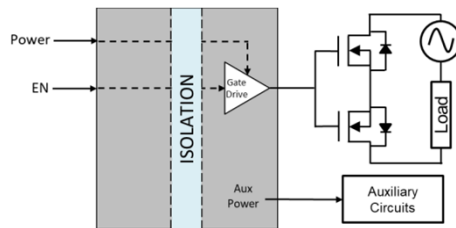


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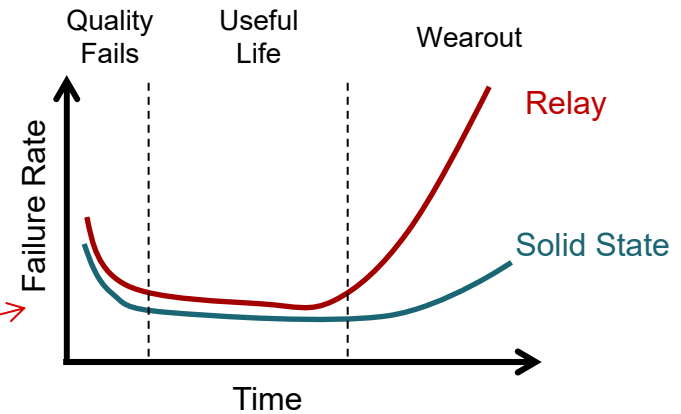


# Relay Limitations in Automotive

## What is a Relay?



Power Supply on a chip

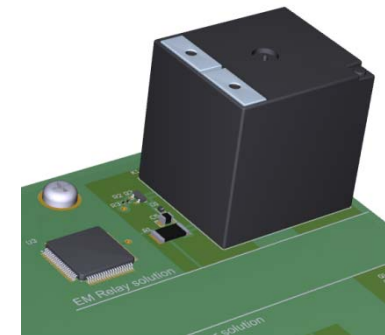


- **Old challenges**

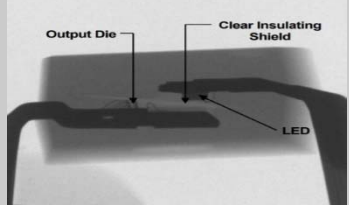
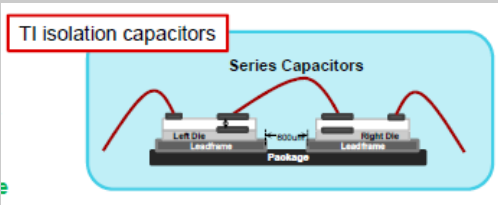
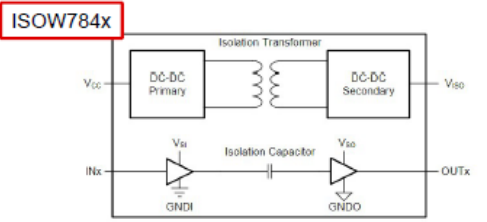
- Reliability in the environment
  - High vibration
  - Dusty and humid environment
- Bulky

- **New Challenges**

- EV driving increased need
- Fast responses
- High voltages



# Path Towards Higher Power and Efficiency

	Opto-Couplers	Silicon Capacitors	Integrated Transformers
	 <p>Source: <a href="https://www.allaboutcircuits.com/technical-articles/beyond-the-optocoupler-understanding-digital-isolators/">https://www.allaboutcircuits.com/technical-articles/beyond-the-optocoupler-understanding-digital-isolators/</a></p>		
Power Xfr	Very low	Low/Expensive	High
Op Temp	-40C → 100C/125C	-40C → 125C	-40C → 125C
Op Temp	-40C → 100C/125C	-40C → 125C	-40C → 125C
Prop Delay	Very Large	Large	Small

***Preferred technology will depend on application needs***

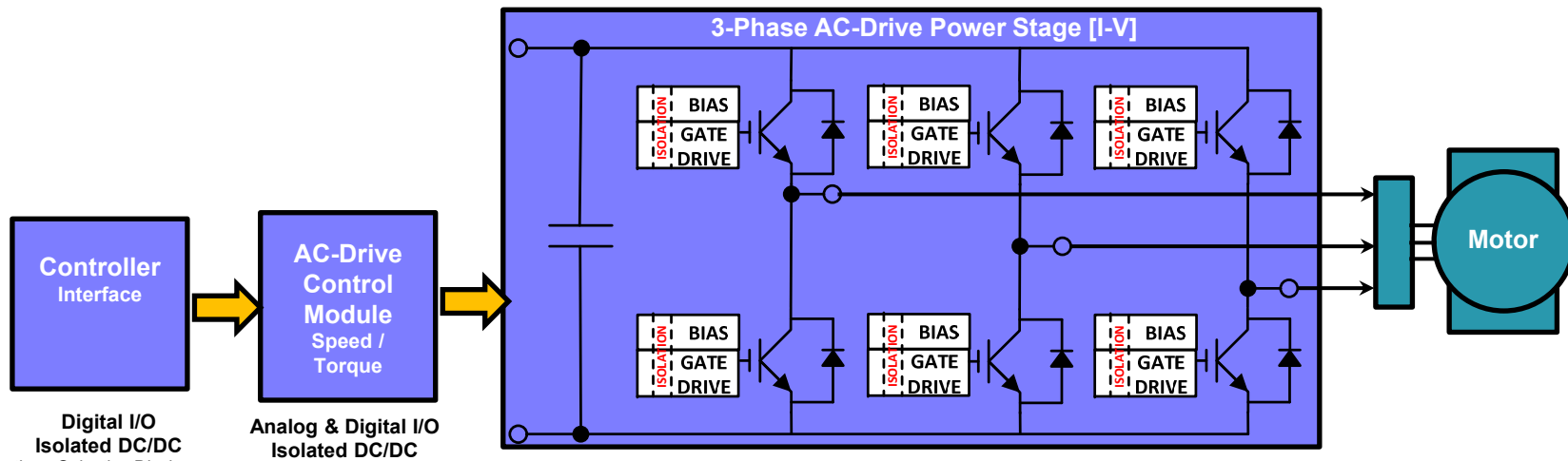
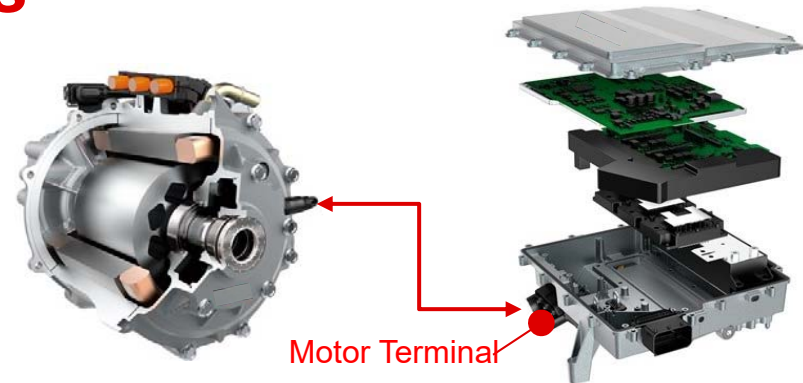
# Application for Isolated Bias Supplies

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# HEV/EV Traction Inverter Bias

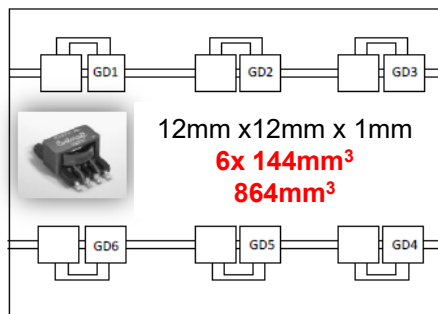
## Enabling Requirements

- Very small size → very high frequency
- Low temperature rise → high efficiency
- Low EMI → Stringent auto requirement
- High isolation → Safety critical

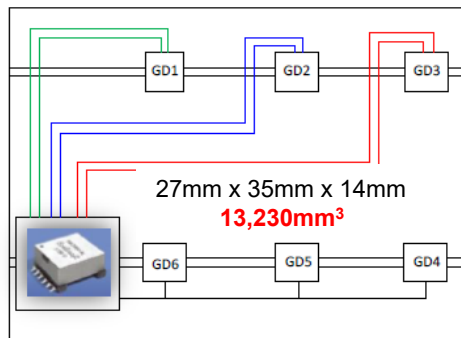


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# Distributed Power Vs. Centralized Power



**Distributed Power**



**Centralized Power**

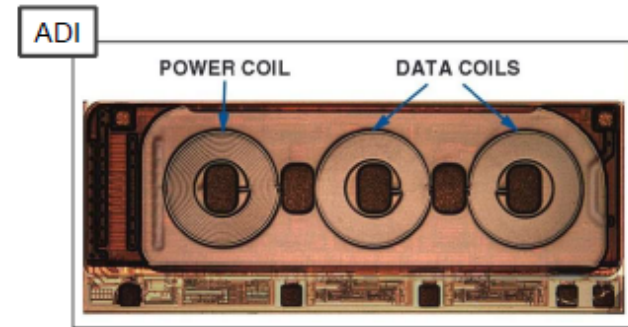
## **Advantages of Separate Power Supply per Gate Driver:**

- **Improved power density**
- **Reduce EMI**
  - Compact routing is good for emission suppression
  - Low EMI techniques in integrated power converters
- **Simplifies PCB layout**
  - Avoid multi-layer PCB with HV and LV line interaction
- **Better bias power quality**
  - Avoid cross regulation issues and eliminate need for post-regulator
- **Distributed weight**
  - Resistant to mechanical vibrations
  - Reduce the transformer profile
- **Distributed power loss for easy cooling**

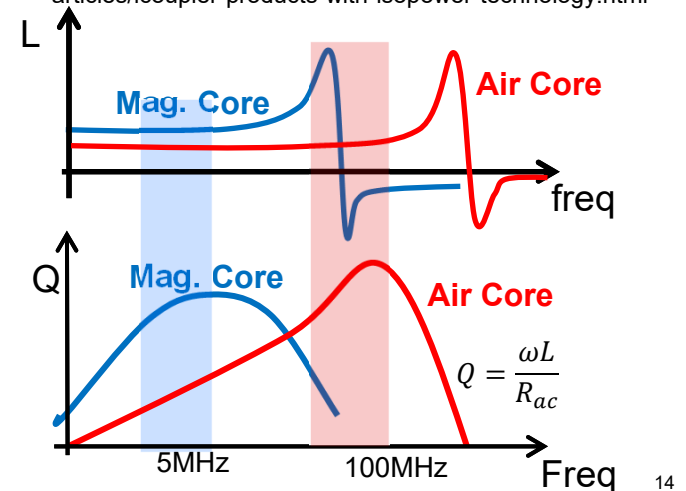
# Path Towards Distributed Bias: Efficiency

## Enabling Requirements

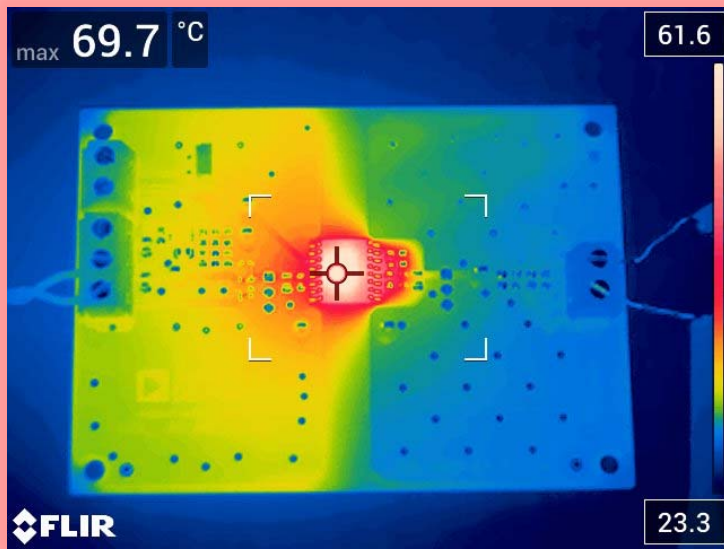
- Very small size → very high frequency
- Low temperature rise → high efficiency
  
- Air core solutions can have very high Q, but at very high frequency
- Magnetic integration enables a better trade-off
  - High Q
  - At much lower frequency



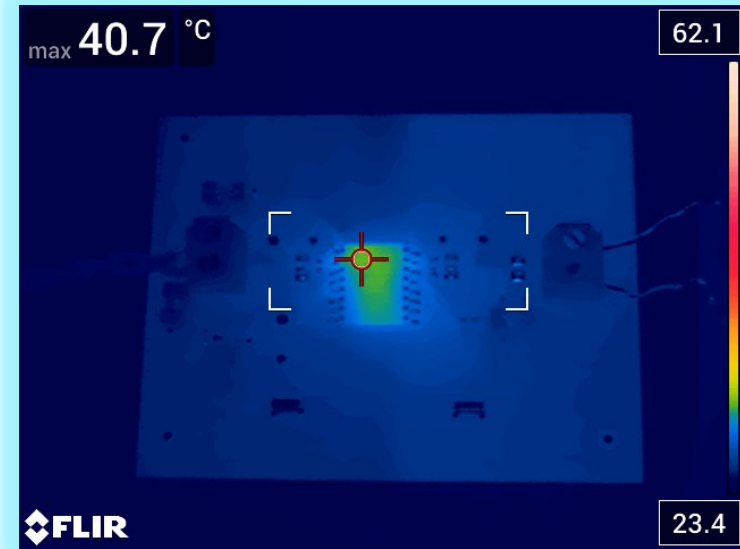
Source: <https://www.analog.com/en/technical-articles/icoupler-products-with-isopower-technology.html>



**Better efficiency, thermal performance → higher density**



**Air Core Solution**

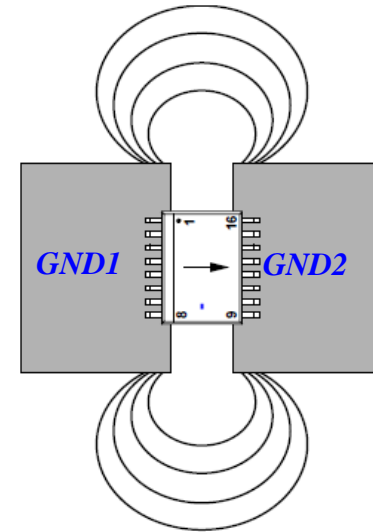
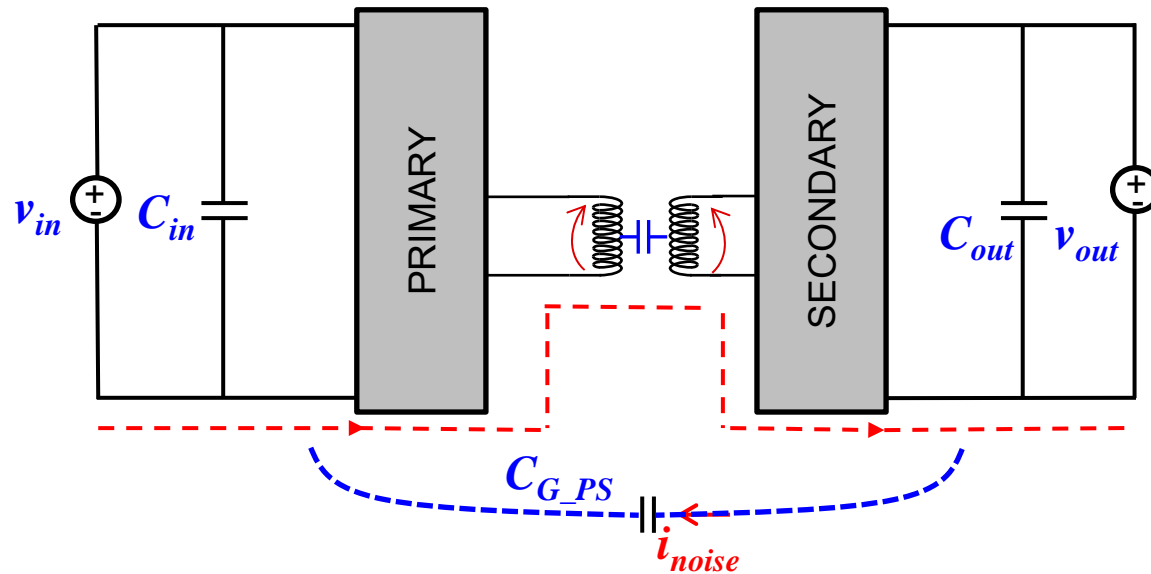


**Magnetic Core (UCC12050)**

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**5 Vin, 5 Vout, 100 mA, 25°C**

# Path Towards Distributed Bias: EMI



- **Methods to minimize EMI**

- **Reduce pri-sec capacitance:** Transformer optimization
- **Minimize the  $dv/dt$ :** Symmetric drives/topologies
- **Reduce the dipole gain:** Additional external cap, stitching capacitors
- **Filters:** Ferrite beads, pre/post regulators



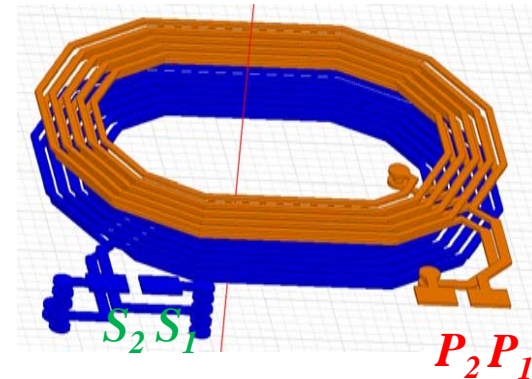
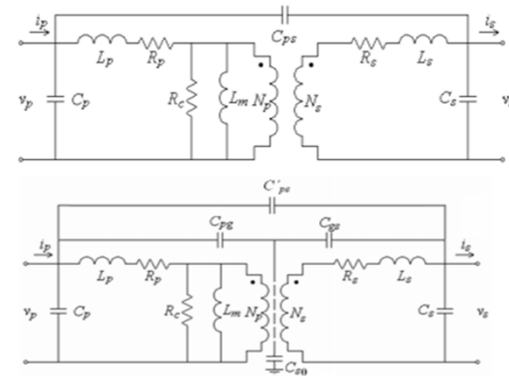
# Reducing Common Mode Currents: Faraday Shields

## Faraday shields:

- Allow magnetic fields to pass
- Are grounded on either side of the isolation barrier

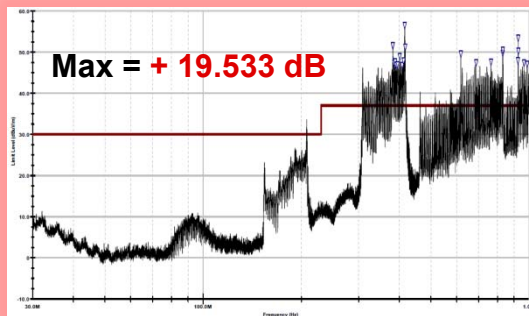
## Benefits:

- Reduced noise from capacitive coupling
- Not available in discrete components with similar size

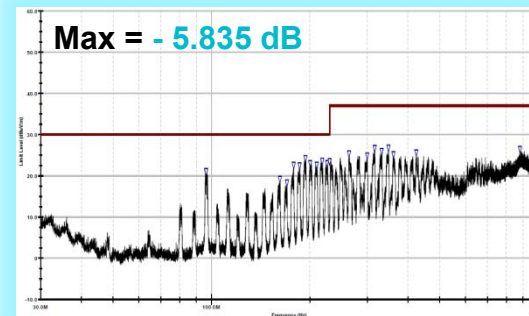


# Better EMI performance = higher power density

*Aircore solution @ 100 mA:*



*Magnetic Core (UCC12050) @ 100 mA:*



- Same (apple-to-apple) EVM configuration: **no ferrite beads , no LDO, no stitch capacitors, on two-layer PCB**
- Tested to CISPR32 Class B Limit, in 10 m chamber

# Conclusions

- Expansion of electronics in automotive is driving the need for integrated power management
- Isolation is critical for EV systems with high voltage present
- Two leading examples of that are solid state relays and distributed bias generation for EVs
- Density (thermals) and EMI are critical requirements to enable the trends
- Fully integrated, isolated power supplies have the opportunity to address these issues